

In the claims:

Please amend the claims as follows:

1. (Currently amended): Electronic component ~~, particularly a surface-mountable radiation-emitting and/or radiation-sensitive electro-optical component (1), with~~ having a plastic housing ~~(10)~~ that includes at least one metallic soldering area ~~(4)~~, characterized in that the surface of the plastic housing ~~(10)~~, except for the metallic soldering area ~~(4)~~, is at least partially covered by an anti-solder coating ~~(6)~~.
2. (Currently amended): Electronic component as in Claim 1, characterized in that the anti-solder coating ~~(6)~~ essentially consists of siloxane.
3. (Currently amended): Electronic component as in Claim 1, characterized in that the anti-solder coating ~~(6)~~ essentially consists of polysiloxane.
4. (Currently amended): Electronic component as in claim 1, characterized in that the anti-solder coating ~~(6)~~ is essentially based on methyl-polysiloxane.
5. (Currently amended): Electronic component as in claim 1, characterized in that the anti-solder coating ~~(6)~~ is essentially based on dimethyl-polysiloxane.
6. (Currently amended): Electronic component as in claim 1, characterized in that the anti-solder coating ~~(6)~~ is essentially based on polyether-modified dimethyl-polysiloxane.
7. (Currently amended): Electronic component as in claim 1, characterized in that the plastic housing ~~(14)~~ contains a radiation-emitting and/or radiation-detecting semiconductor element that is embedded in transparent plastic for the emitted and/or received radiation.

Claims 8-26 (Withdrawn)

27. (New) Electronic component as in claim 1 wherein said component is a surface-mountable radiation-emitting and/or radiation-sensitive electro-optical component.

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28. (New) Electronic component as in claim 1 wherein said component is an unsoldered component.